

**Embedded electronics influence on the strength of carbon fiber laminate**

**Herranen, Henrik; Kers, Jaan; Preden, Jürjo-Sören; Talalaev, Robert; Eerme, Martin; Majak, Jüri; Lend, Henri; Allikas, Georg** Advances in applied materials and electronics engineering III 2014 / p. 239-243

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